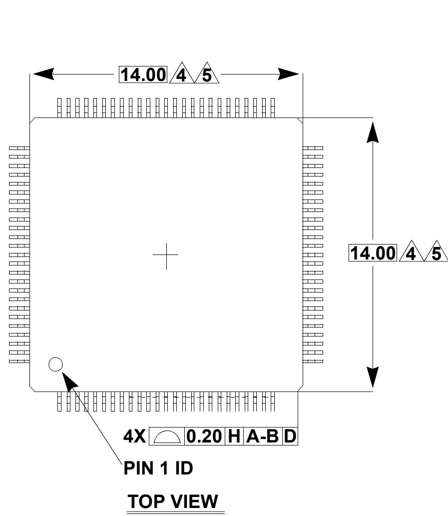
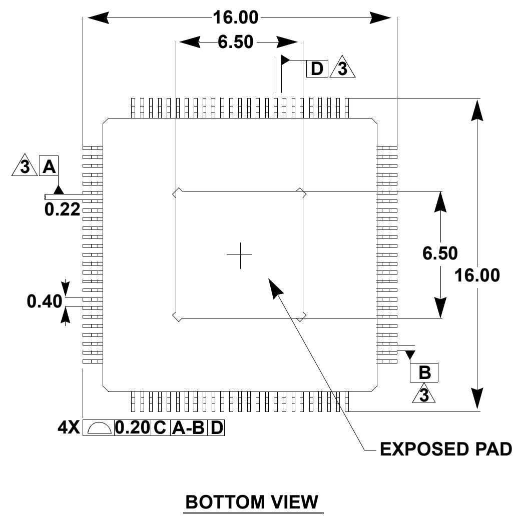
Package Outline Drawing

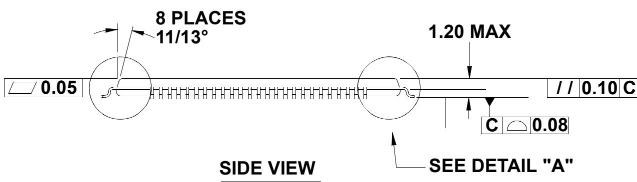
Q128.14x14B

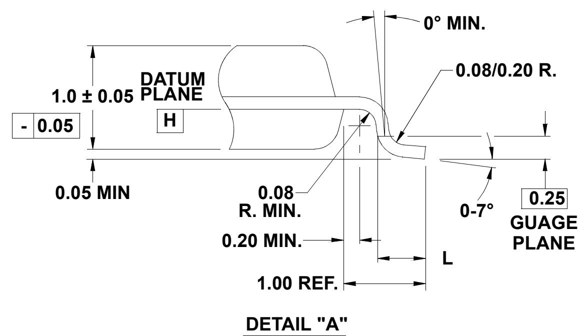
128 LEAD THIN PLASTIC QUAD FLATPACK EXPOSED PAD PACKAGE (TQFP-EP)

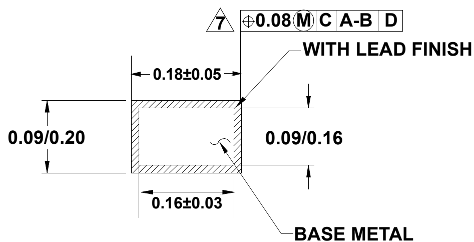
Rev 2, 7/11

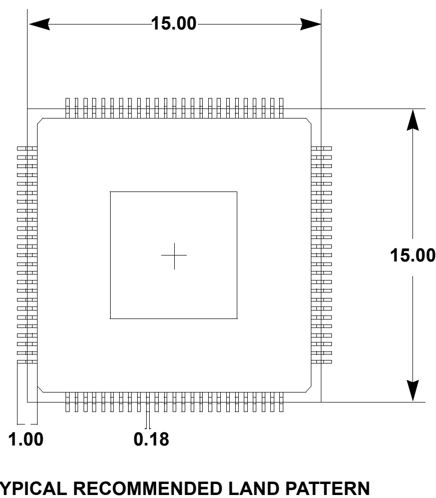












TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. All dimensioning and tolerancing conform to ANSI Y14.5-1982.
2. Datum plane H located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
3. Datums A-B and D to be determined at centerline between leads where leads exit plastic body at datum plane H.
4. Dimensions do not include mold protrusion. Allowable mold protrusion is 0.254mm.
5. These dimensions to be determined at datum plane H.
6. Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package.
7. Does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total at maximum material condition. Dambar cannot be located on the lower radius or the foot.
8. Controlling dimension: millimeter.
9. This outline conforms to JEDEC publication 95 registration MS-026, variation BHB-HU.
10. Dimensions in ( ) are for reference only.
11. Max allowable die thickness to be assembled in this package family is 0.50mm.
12. This outline is not yet JEDEC registered.
13. A1 is defined as the distance from the seating plane to the lowest point of the package body.
14. Exposed die pad shall be coplanar with bottom of package within 0.05mm.
15. Metal area of exposed die pad shall be within 0.30mm of the nominal die pad size.
16. Corner chamfer of exposed die pad shall be within 1.0mm.